

CERTIFICATE OF CONFORMITY

Certificate no.:
C560125

Initial certification date:
28 September 2022

Valid:
28 September 2024 – 27 September 2025

This is to certify that the management system of
**NEPES Corporation & NEPES Ark Cheongju 2
Campus**

587-32, Gwahaksaneop 2-ro, Ochang-eup, Cheongwon-gu, Cheongju-si, Chungcheongbuk-do,
28116, Republic of Korea

and the sites as mentioned in the appendix accompanying this certificate

has been found to conform to Electrostatic Discharge Control Program:
ANSI/ESD S20.20-2021

This certificate is valid for the following scope:

Manufacture of Semiconductor Devices including Wafer Bumping(Au Solder Plating, Cu Pillar Bump, Redistribution Layer Thick Cu and Au Plating, PLP) Wafer Probing and Assembly Process.

The audit has been performed under the supervision of: Kyu Jun Hwang (Lead Auditor)
Client ESD Program Manager: Seung Won Lee

Place and date:
Katy, TX, 03 September 2024

For the issuing office:
DNV - Business Assurance
1400 Ravello Drive, Katy, TX, 77449-5164, USA



Chris Mauterstock
ESD Sector Lead



Certificate no.: C560125
Place and date: Katy, TX, 03 September 2024

Appendix to Certificate

NEPES Corporation & NEPES Ark Cheongju 2 Campus

Locations included in the certification are as follows:

Site Name	Site Address	Site Scope
NEPES Corporation & NEPES Ark Cheongju 2 Campus	587-32, Gwahaksaneop 2-ro, Ochang-eup, Cheongwon-gu, Cheongju-si, Chungcheongbuk-do, 28116, Republic of Korea	Manufacture of Semiconductor Devices including Wafer Bumping(Au Solder Plating, Cu Pillar Bump, Redistribution Layer Thick Cu and Au Plating) Wafer Probing and Assembly Process.
NEPES Corporation Cheongju 1 Campus	116, Gwahaksaneop 3-ro, Ochang-eup, Cheongwon-gu, Cheongju-si, Chungcheongbuk-do, 28125, Republic of Korea	Manufacture of Semiconductor Devices including Wafer Bumping(Au Solder Plating, Cu Pillar Bump, Redistribution Layer Thick Cu and Au Plating) Wafer Probing and Assembly Process.
NEPES Ark Cheongan 3 Campus	30, Nepes-ro, Cheongan-myeon, Goesan-gun, Chungcheongbuk-do, 28049, Republic of Korea	Wafer Probing and Chip Testing for Semiconductor Devices.

